



Product List

SM89S16R1L25, 25MHz 64KB internal flash MCU
SM89S16R1C25, 25MHz 64KB internal flash MCU
SM89S16R1C40, 40MHz 64KB internal flash MCU

General Description

The SM89S16R1 is a single-chip 8-bits micro-controller manufactured in an advanced CMOS process with on chip flash memory. It supports a derivative of the 80C51 microcontroller family. The SM89S16R1 has the same instructions set as the 80C51.

The SM89S16R1 contains a 64K x 8 bits on chip program flash, a volatile 1024 x 8 bits data RAM, four 8-bits I/O ports, one 4-bits I/O port, two 16-bits timer/event counters, and an additional 16-bits timer coupled to capture and compare latches, a two-priority-level, nested interrupt structure, two PWM clock outputs, one serial interfaces (UART bus). For system that requires extra capability the SM89S16R1 can be expanded using standard TTL and LVTTTL compatible memory and logic.

In addition, The SM89S16R1 has two software selectable modes of power saving – IDLE mode and POWER-DOWN mode. The IDLE mode freezes the CPU while allowing the RAM, timer, serial ports, and interrupt system to continue functioning. The POWER-DOWN mode saves the RAM contents but freezes the oscillator, causing all other chip functions to be inoperative.

Feature

- Working Voltage: 3.3V or 5.0V.
- 80C51 Central Processor Unit (CPU).
- 64K x 8 bits on chip flash memory.
- 1024 x 8 bits RAM, expandable externally to 64KB.
- Two standard 16-bits timers/counters
- An additional 16-bits timer/counter coupled to a capture and compare register.
- Two 8-bits / 5-bits resolution Pulse-Width-Modulation (PWM) outputs
- Four 8-bits I/O ports.(For PDIP package)
- Four 8-bits I/O ports plus one 4-bits I/O port. (For PLCC or QFP package)
- Full-duplex UART
- 8 interrupt sources with 2 priority levels
- Extended temperature range (-40°C to +85°C)
- Software enable/disable ALE output pulse
- Wake-up from POWER-DOWN mode by INT0/INT1, RTCI or H/W RESET.
- RTC (Real Time Clock) function.
- Four channels 6-bits Analog to Digital Converter (ADC).

Ordering Information

SM89S16R1ihhk
yyymm

i: process identifier {L=3.0V~3.6V,C=4.5V~ 5.5V}
hh: working clock in MHz {25, 40}
k: package type postfix {as below table}
yy: year mm: month
v: version identifier { , A, B, ...}

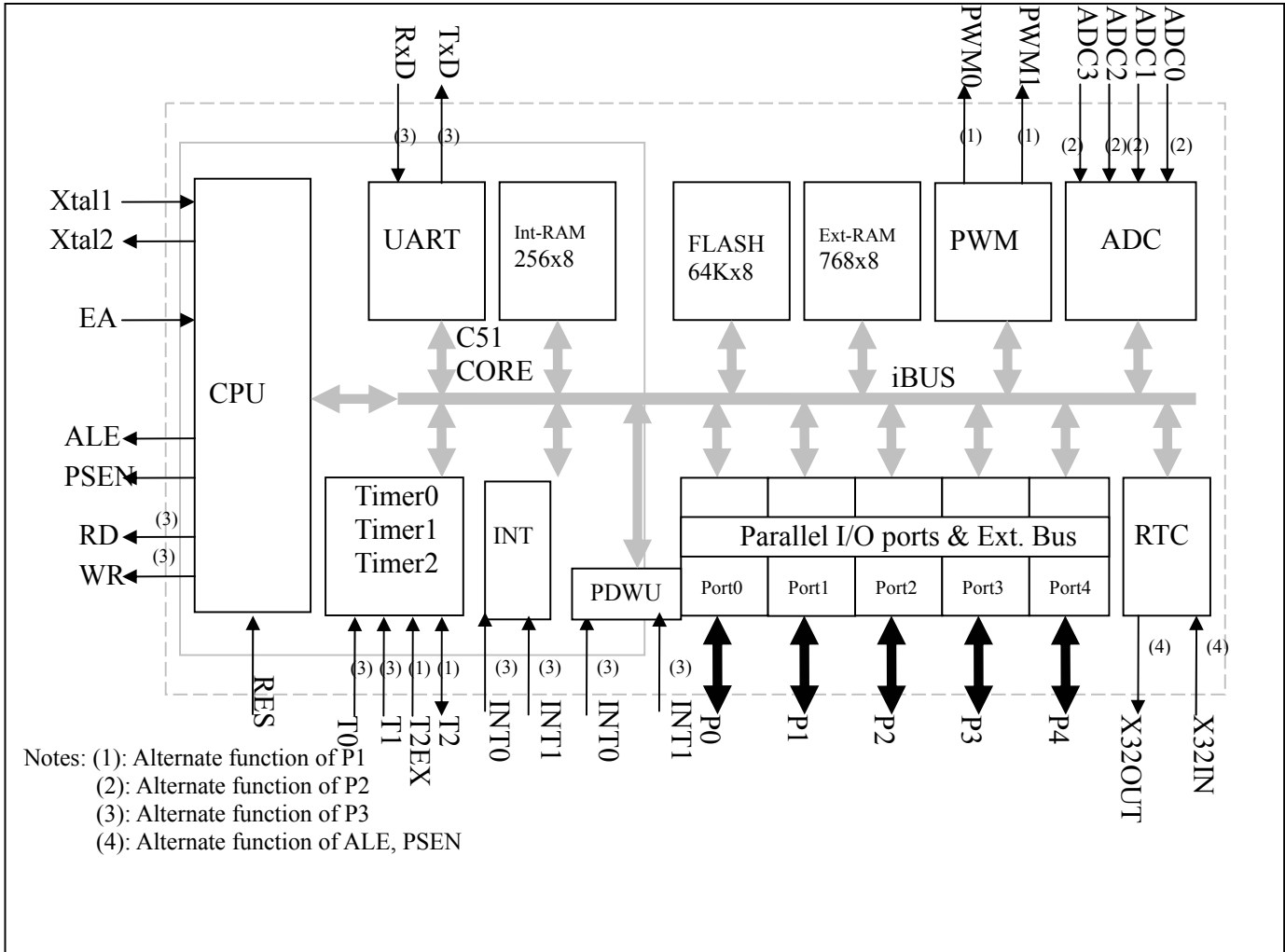
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Block Diagram



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Pin Description

MNEMONIC	PDIP 40 pin	PQFP 44 Pin	PLCC 44 pin	Names and Functions
VDD	40	38	44	Power supply: +5V or +3.3V power supply pin during normal operations and power saving modes.
P0.0 – P0.7	39,38,37,36 35,34,33,32	37,36,35,34 33,32,31,30	43,42,41,40 39,38,37,36	Port 0: Port 0 is an open-drain, bidirectional I/O port. Port 0 pins that have 1s written to them become floating and can be used as high- impedance inputs. Port 0 is also the multiplexed low-order address and data bus during accesses to external program and data memory. In this application, it uses strong internal pull-ups when emitting 1s. Port Pin Alternative function P0.0 AD0 P0.1 AD1 P0.2 AD2 P0.3 AD3 P0.4 AD4 P0.5 AD5 P0.6 AD6 P0.7 AD7
P1.0 – P1.7	1,2,3,4, 5,6,7,8	40,41,42,43, 44,1,2,3	2,3,4,5, 6,7,8,9	Port 1: An 8-bits bidirectional I/O port with internal pull-ups on all pins. Port 1 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 1 pins that are externally pulled low will source current because of the internal pull-ups. (See DC Electrical Characteristics: IIL). Port Pin Alternative function P1.0 T2: TIMER2 clock output P1.1 T2EX: TIMER2 reload/capture DIR. P1.4 PWM0: PWM channel 0 output P1.5 PWM1: PWM channel 1 output
RST	9	4	10	Reset: A high on this pin for two machine cycles while the oscillator is running, resets the device. An internal resistor to VSS permits a power-on reset using only an external capacitor to VCC.
P2.0 – P2.7	21,22,23,24, 25,26,27,28	18,19,20,21 22,23,24,25	24,25,26,27, 28,29,30,31	Port 2: Port 2 is an 8-bits bidirectional I/O port with internal pull-ups. Port 2 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 2 pins that are externally being pulled low will source current because of the internal pull-ups. (See DC Electrical Characteristics: IIL). Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that uses 16-bits addresses (MOVX @DPTR). In this application, it uses strong internal pull-ups when emitting 1s. During accesses to external data memory that uses 8-bits addresses (MOV @Ri), port 2 emits the contents of the P2 special function register. Port Pin Alternative function P2.0 A8 P2.1 A9 P2.2 A10 P2.3 A11 P2.4 A12/ADC0 P2.5 A13/ADC1 P2.6 A14/ADC2 P2.7 A15/ADC3

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MNEMONIC	PDIP 40 pin	PQFP 44 Pin	PLCC 44 pin	Names and Functions
P3.0 – P3.7	10,11,12,13 14,15,16,17	5,7,8,9, 10,11,12,13	11, 13,14,15, 16,17,18,19	<p>Port 3: Port 3 is an 8-bits bidirectional I/O port with internal pull-ups. Port 3 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 3 pins that are externally being pulled low will source current because of the pull-ups. (See DC Electrical Characteristics: IIL). Port 3 also serves the special features.</p> <p>Port Pin Alternative function P3.0 RxD UART input P3.1 TxD UART output P3.2 #EX0 external interrupt 0 P3.3 #EX1 external interrupt 1 P3.4 T0: Timer 0 external input P3.5 T1: Timer 1 external input P3.6 #WR External data memory write strobe P3.7 #RD External data memory read strobe</p>
ALE/X32OUT	30	27	33	<p>Address Latch Enable: Output pulse for latching the low byte of the address during an access to external memory. In normal operation, ALE is emitted twice every machine cycle, and can be used for external timing or clocking. Note that one ALE pulse is skipped during each access to external data memory. Setting SFR SCONF.0 can disable ALE. With this bits set, ALE will be active only during a MOVX instruction. X32OUT: The 32.768KHz crystal output for RTC function.</p>
#PSEN/X32IN	29	26	32	<p>Program Store Enable: The read strobe to external program memory. When executing code from the external program memory, #PSEN is activated twice each machine cycle, except that two #PSEN activations are skipped during each access to external data memory. #PSEN is not activated during fetches from internal program memory. X32IN: The 32.768KHz crystal input for RTC function.</p>
#EA	31	29	35	<p>External Access Enable: #EA must be externally held low to enable the device to fetch code from external program memory locations. If #EA is held high, the device executes from internal program memory.</p>
X1	19	15	21	<p>Crystal 1: Input to the inverting oscillator amplifier and input to the internal clock generator circuits.</p>
X2	18	14	20	<p>Crystal 2: Output from the inverting oscillator amplifier.</p>

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SFR Mapping

The special function register of SM89S16R1 fall into the following categories

- C51 CORE register: ACC, B, DPL, DPH, PSW, SP
- I/O ports: P0,P1, P2, P3, P4
- Timer/Counter register: T2CON, T2MOD, TCON, TMOD, TH0, TH1, TH2, TL0, TL1, TL2, RCAP2L, RCAP2H
- UART I/O register: SBUF, SCON
- Power and system control register: PCON, SCONF
- Interrupt system register: IP, IE, IP1, IE1, IFR
- PWM output register: PWMC0, PWMC1, PWMD0, PWMD1, P1CON
- ADC register: ADCSC, ADCD, P2CON
- RTC register: RTCC, RTCS
- LED Driving Capability Control: LEDP0, LEDP1, LEDP2, LEDP3, LEDP4

Table 1 SFR Map

\$F8								\$FF
\$F0	B 0000 0000							\$F7
\$E8								\$EF
\$E0	ACC 0000 0000							\$E7
\$D8	P4 xxxx 1111							\$DF
\$D0	PSW 0000 0000			PWMC0 0000 0000	PWMC1 0000 0000			\$D7
\$C8	T2CON 0000 0000	T2MOD xxxx xx00	RCAP2L 0000 0000	RCAP2H 0000 0000	TL2 0000 0000	TH2 0000 0000		\$CF
\$C0								\$C7
\$B8	IP 0000 0000	IP1 0000 0000					SCONF 0000 0000	\$BF
\$B0	P3 1111 1111			PWMD0 0000 0000	PWMD1 0000 0000			\$B7
\$A8	IE 0000 0000	IE1 0000 0000	IFR 0000 0000					\$AF
\$A0	P2 1111 1111	RTCS 0000 0000	RTCC 0000 0000					\$A7
\$98	SCON 0000 0000	SBUF xxxx xxxx		P1CON 0000 0000	P2CON 0000 0000			\$9F
\$90	P1 1111 1111		LEDP0 0000 0000	LEDP1 0000 0000	LEDP2 0000 0000	LEDP3 0000 0000	LEDP4 0000 0000	\$97
\$88	TCON 0000 0000	TMOD 0000 0000	TL0 0000 0000	TL1 0000 0000	TH0 0000 0000	TH1 0000 0000	ADCSC 0000 0000	ADCD 0000 0000
\$80	P0 1111 1111	SP 0000 0111	DPL 0000 0000	DPH 0000 0000				PCON 0000 0000

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Table 2 : All SFR list (8051, I/O, Timer, UART, System, Interrupt, RAM Control, PWM, RTC, ADC)

Symbol	Description	Direct	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	RESET
8051 Core											
ACC*	Accumulator	E0									00H
B	B register	F0									00H
SP	Stack Pointer	81H									07H
PSW*	Process Status	D0H	CY	AC	F0	RS1	RS0	OV		P	00H
DPTR	Data Pointer (2 Bytes)										
DPH	Data Pointer High	82H									00H
DPL	Data Pointer Low	83H									00H
I/O PORT											
P0*	Port 0	80H	P0.7	P0.6	P0.5	P0.4	P0.3	P0.2	P0.1	P0.0	FFH
P1*	Port 1	90H	P1.7	P1.6	P1.5	P1.4	P1.3	P1.2	P1.1	P1.0	FFH
P2*	Port 2	A0H	P2.7	P2.6	P2.5	P2.4	P2.3	P2.2	P2.1	P2.0	FFH
P3*	Port 3	B0H	P3.7	P3.6	P3.5	P3.4	P3.3	P3.2	P3.1	P3.0	FFH
P4*	Port 4	D8H					P4.3	P4.2	P4.1	P4.0	XFH
P1CON	P1 Control	9BH					PWM1E	PWM0E	-	-	00H
P2CON	P2 Control	9CH	ADC3E	ADC2E	ADC1E	ADC0E			-	-	00H
TIMER / Counter											
TCON*	Timer Control register	88H	TF1	TF1	TF0	TR0	IE1	IT1	IE0	IT0	00H
THL0	Timer 0 (2 Bytes)										
TH0	Timer 0 High	8CH									00H
TL0	Timer 0 Low	8AH									00H
THL1	Timer 1 (2 Bytes)										
TH1	Timer 1 High	8DH									00H
TL1	Timer 1 Low	8BH									00H
T2CON*	Timer 2 Control	C8H	TF2	EXF2	RCLK	TCLK	EXEN2	TR2	CT2	CPRL2	00H
T2MOD	Timer 2 Mode	C9H							T2OE	DCEN	X0H
RCAP2HL	Reload/Capture (2 bytes)										
RCAP2H	RCAP2 High	CBH									00H
RCAP2L	RCAP2 Low	CAH									00H
THL2	Time 2 (2 bytes)										
TH2	Timer 2 High	CDH									00H
TL2	Time 2 Low	CCH									00H
UART											
SCON*	UART Control	98H	SM0	SM1	SM2	REN	TB8	RB8	TI	RI	00H
SBUF	UART Buffer	99H									XXH
A/D Converter											
ADSCR	ADC status & control	8EH	COM	CON	ADCSS1	ADCSS0	CH1	CH0			00H
ADCD	ADC data register	8FH	AD.5	AD.4	AD.3	AD.2	AD.1	AD.0			00H
Real Timer Clock (RTC)											
RTCS	RTC Status	A1H	RT Cen	Stable	Sec.5	Sec.4	Sec.3	Sec.2	Sec.1	Sec.0	00H
RTCC	RTC Control	A2H	Int_sel.1	Int_sel.0	Min.5	Min.4	Min.3	Min.2	Min.1	Min.0	00H
PWM output											
PWMC0	PWM 0 Control	D3H						PBS	PFS1	PFS0	00H
PWMC1	PWM 1 Control	D4H						PBS	PFS1	PFS0	00H
PWMD0	PWM 0 Data	B3H	PWMD.7	PWMD.6	PWMD.5	PWMD.4	PWMD.3	PWMD.2	PWMD.1	PWMD.0	00H
PWMD1	PWM 1 Data	B4H	PWMD.7	PWMD.6	PWMD.5	PWMD.4	PWMD.3	PWMD.2	PWMD.1	PWMD.0	00H
Power and System											
PCON	Power Control register	87H	SMOD						PD	IDLE	00H
SCONF	System Control	BFH				PDWUE			OME	ALEI	00H
Interrupt system											
IE*	Interrupt Enable	A8H	EA		ET2	ES0	ET1	EX1	ET0	EX0	00H
IE1	Interrupt Enable 1	A9H					EADC	ERTC			00H
IFR	Interrupt Flag 1	AAH					ADCIF	RTCIF			00H
IP*	Interrupt Priority	B8H			PT2	PS0	PT1	PX1	PT0	PX0	00H
IP1	Interrupt Priority 1	B9H					PADC	PRTC			00H
LED Driving Capability Control											
LEDP 0	LED output in P0	92H									00H
LEDP 1	LED output in P1	93H									00H
LEDP 2	LED output in P2	94H									00H
LEDP 3	LED output in P3	95H									00H
LEDP 4	LED output in P4	96H									00H

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Target Spec.
Absolute Rating

Symbol	Description	Min.	Typ.	Max.	Unit.	Remarks
TA	Operating temperature	-40	25	85	°C	Ambient temperature under bias
TS	Storage temperature	-55	25	155	°C	Damage to devices could occur
VCC5	Supply voltage	4.5	5.0	5.5	V	
VCC3.3	Supply voltage	3.0	3.3	3.6	V	
Fosc 25	Oscillator Frequency			25	MHz	For 3.3V application
Fosc 40	Oscillator Frequency			40	MHz	For 5.0V application

DC Characteristic

VCC = 5V (±10%), VSS=0V TA= -40°C to 85°C

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS		UNIT
			MIN	MAX	
VCC	Supply Voltage		4.5	5.5	V
ICC	Supply current operating	See notes 1 f _{CLK} = 12MHz VCC = 5.5V		20	mA
IID	Supply current IDLE Mode	See note 2 f _{CLK} = 12MHz VCC = 5.5V		6.5	mA
IPD	Supply current Power-Down MODE RTC Disable	See note 3 ; VCC (= 5.5V)		30	µA
	Supply current Power-Down MODE RTC Enable	See note 3 ; VCC (= 5.5V)		80	µA
INPUT					
VIL1	Input LOW voltage, P0, P1, P2, P3, P4, /EA		-0.5	0.8	V
VIL2	Input LOW voltage, RES, XTAL1		0	0.8	V
VIH1	Input HIGH voltage, P0, P1, P2, P3, P4, /EA		2.0	V _{CC} +0.5	V
VIH2	Input HIGH voltage, RES, XTAL1		70%VCC	V _{CC} +0.5	V
IIL	Input current LOW level Port 1,2,3,4	VIN = 0.45V		-75	µA
ITL	Transition current High to Low Port 1,2,3,4	VIN = 2.0 V		-650	µA
ILI	Input leakage current ,Port 0	0.45V < VIN < VCC-0.3V		±10	µA
OUTPUT					
VOL1	Output LOW voltage, Port 0,ALE, /PSEN	IOL = 8mA , VCC=5.0V		0.45	V
VOL2	Output LOW voltage, Port 1, 2, 3, 4	IOL = 6.5mA , VCC =5.0V		0.45	V
VOH1	Output High voltage Port0 ALE, /PSEN	IOH = -800µA , VCC =5.0V	2.4		V
VOH2	Output High voltage Port 1,2,3,4	IOH = -60µA , VCC =5.0V	2.4		V
RRST	Internal RESET pull-down resistor		50	300	kΩ
CIO	Pin capacitance	Test freq=1MHz, TA=25°C		10	pF

VCC = 3.3V (±10%), VSS=0V , TA= -40°C to 85°C

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS		UNIT
			MIN	MAX	
VCC	Supply Voltage		3.0	3.6	V
ICC	Supply current operating	See note 1 f _{CLK} = 12MHz VCC = 3.6V		10	mA
IID	Supply current IDLE Mode	See note 2 f _{CLK} = 12MHz VCC = 3.6V		5	mA
IPD	Supply current Power-Down MODE RTC Disable	See note 3 ; VCC (= 3.6V)		20	µA
	Supply current Power-Down MODE RTC Enable	See note 3 ; VCC (= 3.6V)		30	µA
INPUT					

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VIL1	Input LOW voltage, P0, P1, P2, P3, P4, /EA	VCC = 3.6V	0	0.2 VCC -0.2	V
VIL2	Input LOW voltage, RST	VCC = 3.6V	0	0.2 VCC -0.2	V
VIL3	Input LOW voltage, XTAL1	VCC = 3.6V	0	0.2 VCC -0.2	V
VIH1	Input HIGH voltage, P0, P1, P2, P3, P4, /EA	VCC = 3.6V	0.6 VCC -0.4	VCC + 0.2	V
VIH2	Input HIGH voltage, RST	VCC = 3.6V	0.6 VCC -0.4	VCC + 0.2	V
VIH3	Input HIGH voltage, XTAL1	VCC = 3.6V	0.8 VCC	VCC + 0.2	V
IIN1	Input current LOW level Port 1,2,3,4	VCC = 3.0V ~3.6V, VIN = 0.45V.	-10	50	μA
ITL	Transition current High to Low Port 1,2,3,4	See note 4 VCC = 3.6V, VIN = 2.0 V	-75	400	μA
ILI	Input leakage current P0, /EA	VCC = 3.0V ~3.6V, 0.45V<VIN<VCC	-10	10	μA
OUTPUT					
VOL1	Output LOW voltage, Port 0,ALE, /PSEN	IOL = 6mA · VCC =3.3V		0.4	V
VOL2	Output Low voltage Port 1,2,3,4	IOL = 5mA · VCC =3.3V		0.4	V
VOH1	Output High voltage Port0, ALE, /PSEN	IOH =-300uA · VCC =3.3V	2.4		V
VOH2	Output High voltage Port 1,2,3,4	IOH =-20μA · VCC =3.3V	2.4		V
ISK1	Sink Current Port 1, 2, 3, 4	VCC = 3.3V, VIN = 0.4 V		6	mA
ISK2	Sink Current Port 0,ALE, /PSEN	VCC = 3.3V, VIN = 0.4 V		8	mA
ISR1	Source Current Port 1, 2, 3, 4	VCC = 3.3V, VIN = 2.4 V		-80	uA
ISR2	Source Current Port 0,ALE, /PSEN	VCC = 3.3V, VIN = 2.4 V		-8	mA
RRST	Internal RESET pull-down resistor		50	300	kΩ
CIO	Pin capacitance	Test freq=1MHz, TA=25°C		10	pF

NOTES FOR DC ELECTRICAL CHARACTERISTICS

- The operating supply current is measured with all output disconnected; XTAL1 driven with tr = tf = 5ns; VIL = VSS+0.5V; VIH=VCC-0.5V; XTAL2 not connect; /EA=RST=Port0=VDD;
- The IDLE MODE supply current is measured with all output pins disconnected; XTAL1 driven with tr = tf = 5ns; VIL = VSS+0.5V; VIH=VCC-0.5V; XTAL2 not connect; /EA=Port0=VDD;
- The POWER-DOWN MODE supply current is measured with all output pins disconnected; VIL = VSS+0.5V; VIH=VCC-0.5V; XTAL2 not connect; /EA= Port0=VDD;
- Port 1, 2, 3, and 4 sources a transition current when they are being externally driven from HIGH to LOW. The transition current reaches its maximum value when VIN is approximately 2V.
- Capacities loading on port 0 and 2 may cause spurious noise to be superimposed on VOL of ALE and port 1, 3, and 4. The noise is due to external bus capacitance discharging into port 0 and port 2 pins when these pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100pF), the noise pulse on the ALE pin may exceed 0.8V. In such cases, it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt trigger STROBE input.

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AC Characteristic

VCC=3.3V±10%, VSS=0V, tclk min = 1/ fmax(maximum operating frequency)

TA= -40°C to +85°C

CL=100pF for Port0, ALE and /PSEN; CL=80pF for all other outputs unless otherwise specified.

Symbol	FIGURE	PARAMETER	MIN	MAX	UNIT
External Clock drive into XTAL1					
tCLK	4	Xtal1 Period	40(1)	-	ns
tCLKH	4	Xtal1 HIGH time	20	-	ns
tCLKL	4	Xtal1 LOW time	20	-	ns
tCLKR	4	XTAL1 rise time	-	10	ns
tLLIV	4	XTAL1 fall time	-	10	ns
tCYC	4	Controller cycle time = tCLK / 4	3.33	-	Ns

NOTES:

1. Operating at 25MHz.

Symbol	FIGURE	PARAMETER	MIN	MAX	UNIT
Program Memory					
1/tCLK	7	System clock frequency	3.0	25	MHz
tLHLL	7	ALE pulse width	2tCLK-40		ns
tAVLL	7	Address valid to ALE low	tCLK-40		ns
tLLAX	7	Address hold after ALE low	tCLK-30		ns
tLLIV	7	ALE LOW to valid instruction in		4tCLK-100	ns
tLLPL	7	ALE LOW to /PSEN LOW	tCLK-30		ns
tPLPH	7	/PSEN pulse width	3tCLK-45		ns
tPLIV	7	/PSEN LOW to valid instruction in		3tCLK-105	ns
tPXIX	7	Input instruction hold after /PSEN	0		ns
tPXIZ	7	Input instruction float after /PSEN		tCLK -25	ns
tAVIV	7	Address to valid instruction in		5tCLK-105	ns
tPLAZ	7	/PSEN low to address float		10	ns
Data Memory					
tAVLL	8,9	Address valid to ALE LOW	tCLK-40		ns
tLLAX	8,9	Address hold after ALE LOW	tCLK-35		ns
tRLRH	8	/RD pulse width	6tCLK-100		ns
tWLWH	9	/WR pulse width	6tCLK-100		ns
tRLDV	8	/RD LOW to valid data in		5tCLK-165	ns
tRHDX	8	Data hold after /RD	0		ns
tRHDZ	8	Data float after /RD		2tCLK-70	ns
tLLDV	8	ALE LOW to valid data in		8tCLK-150	ns
tAVDV	8	Address to valid data in		9tCLK-165	ns
tLLWL	8,9	ALE LOW to /RD or /WR LOW	3tCLK-50	3tCLK+50	ns
tAVWL	8,9	Address valid to /WR or /RD LOW	4tCLK-130		ns
tQVWX	9	Data valid to /WR transition	tCLK-50		ns
tQVWH	9	Data before /WR	7tCLK-150		ns
tWHQX	9	Data hold after /WR	tCLK-50		ns
tRLAZ	8	/RD LOW to address float		0	ns
tWHLH	8,9	/RD or /WR HIGH to ALE HIGH	tCLK-40	tCLK+40	ns
UART					
tXLXL	10	Serial port clock time	12tCLK		ns
tQVXH	10	Output data setup to clock rising edge	10tCLK-133		ns
tXHQX	10	Output data hold after clock rising edge	2tCLK-117		ns
tXHDX	10	Input data hold after clock rising edge	0		ns
tXHDV	10	Clock rising edge to input data valid		10tCLK-133	ns

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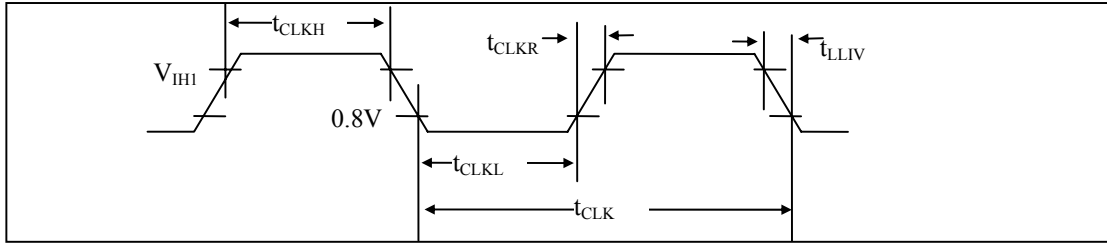


Figure 4 External Clock Drive waveform

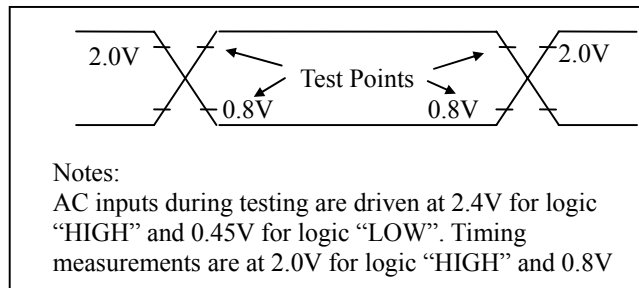


Figure 5 AC Testing Input/Output

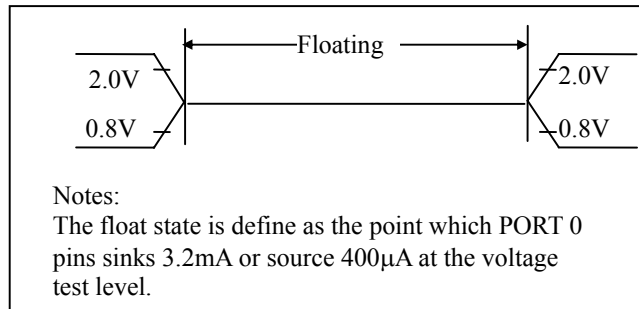


Figure 6 AC Testing, Floating Waveform

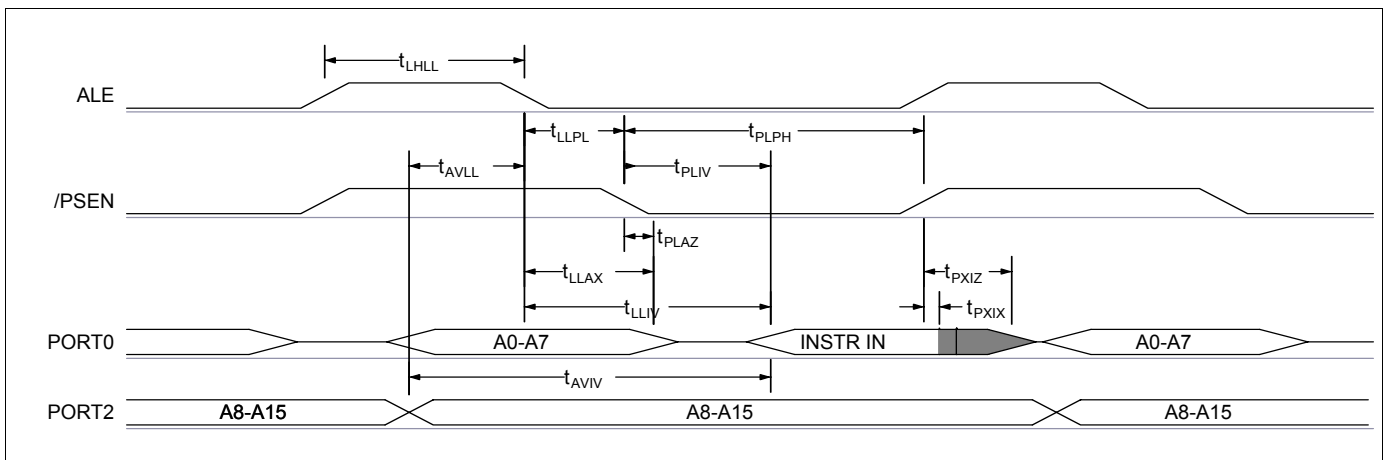


Figure 7 External Program Memory Read Cycle

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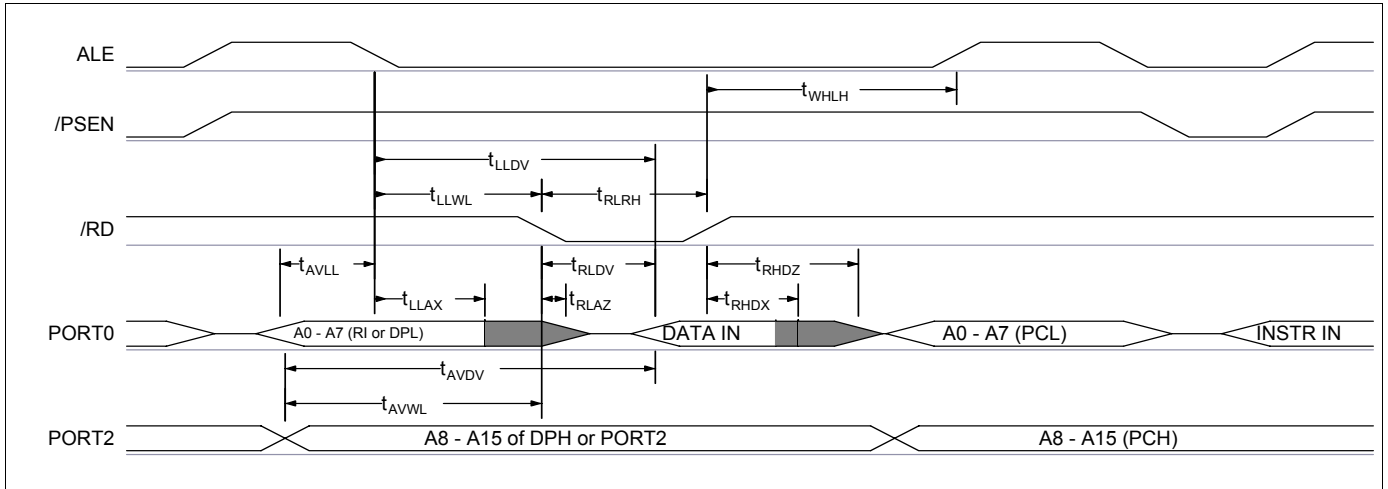


Figure 8 External Data Memory read cycle

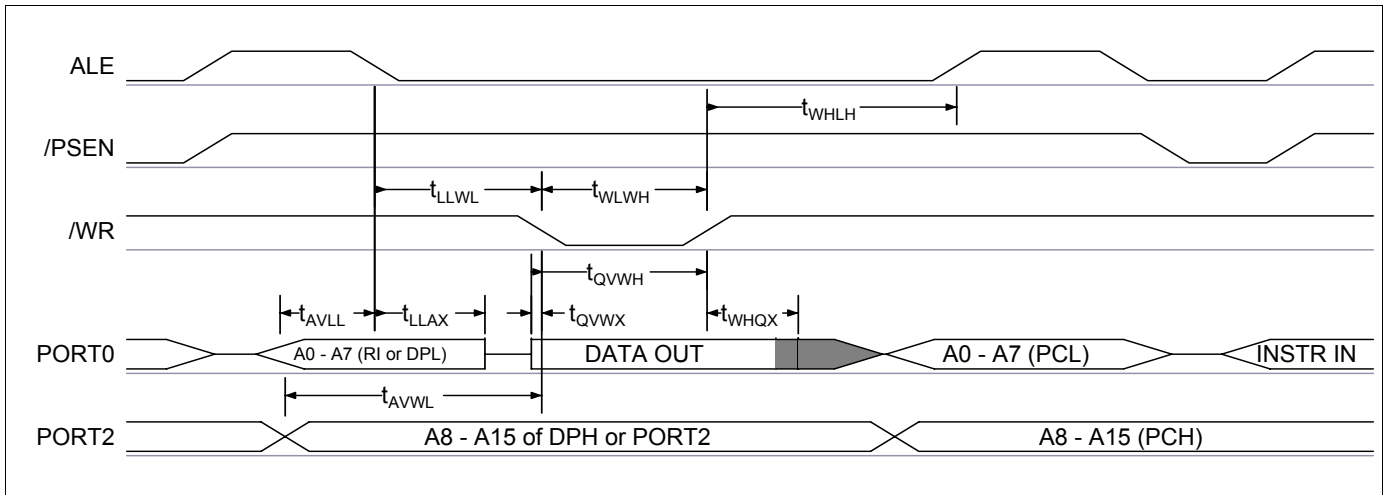


Figure 9 External Data Memory write cycle

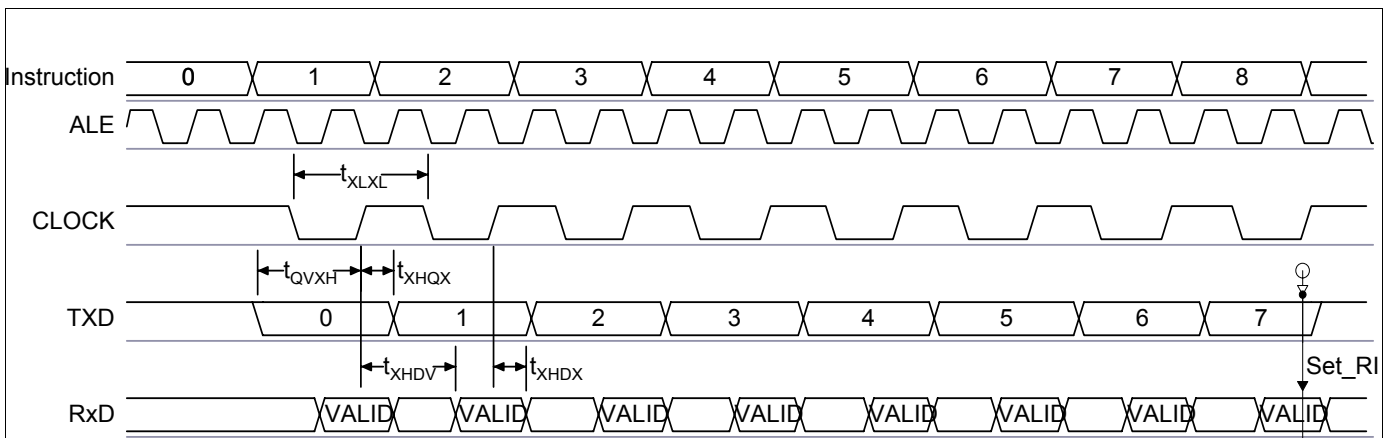


Figure10 UART waveform in Shift Register MODE

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Function Description

The SM89S16R1 is a stand-alone high-performance microcontroller designed for use in many applications, such as LCD monitor, instrumentation, or high-end consumer applications.

In addition to the 80C51 standard functions, the device provides a number of dedicated hardware functions for these applications.

The SM89S16R1 is a control-oriented CPU with on-chip program and data memory. It can be extended with external data memory up to 64K bytes. For system requiring extra capability, the SM89S16R1 can be enhanced by using external memory and peripherals.

The SM89S16R1 has two software selectable modes of saving power consumption : IDLE and POWER-DOWN. The IDLE mode freezes the CPU while allowing the RAM, timer, serial ports and interrupt system to continue functioning. The POWER-DOWN mode save the RAM contents but freezes the oscillator causing all other chip functions to be inoperative. The POWER-DOWN mode can be terminated by H/W reset, or by any one of the two external interrupt or RTCI function.

CPU

The CPU of SM89S16R1 is compatible to standard 80C51. The structure of this CPU is shown as FIGURE 11. It contains Instruction Register (IR), Instruction Decoder, and Program Counter (PC), Accumulator (ACC), B Register, and control logic. This CPU provides a 8-bits bi-direction bus to communicate with other blocks in the chip. The address and data are transferred through on the same 8-bits bus.

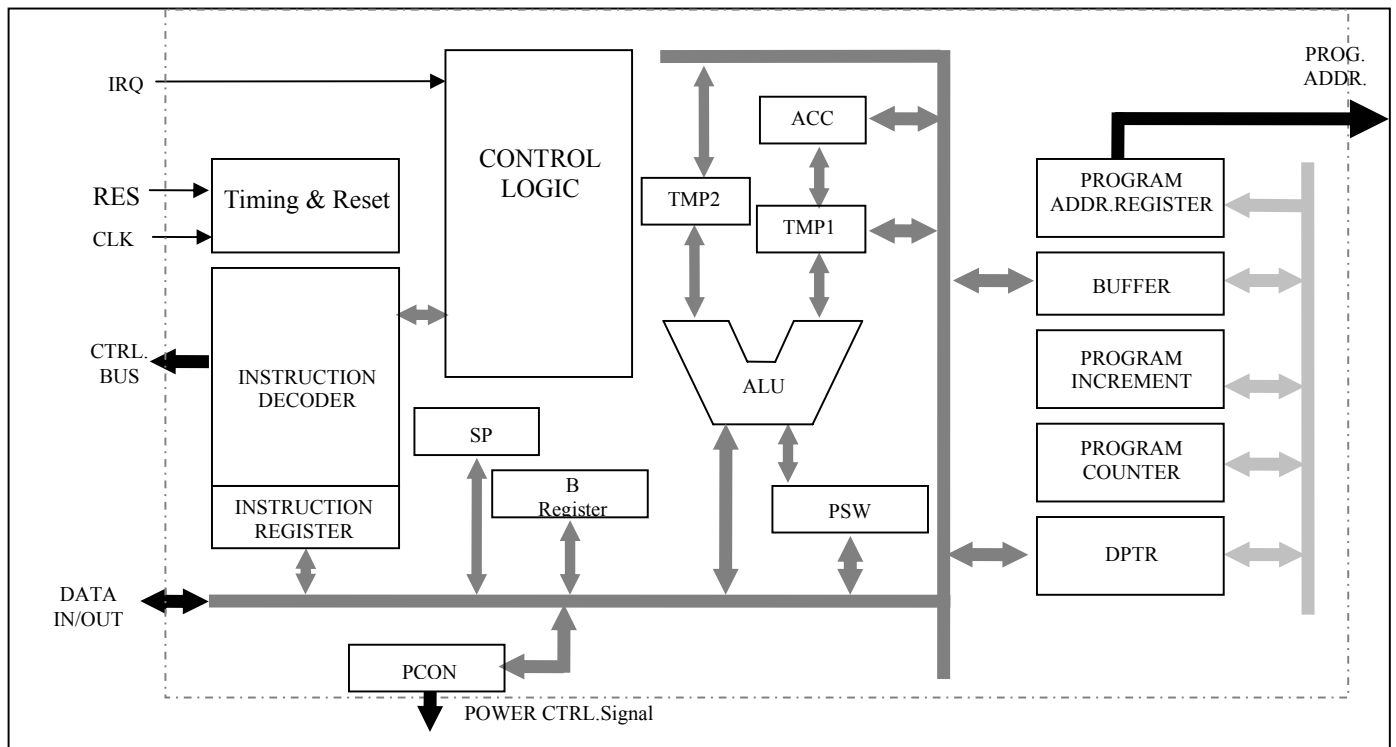


Figure 11 The CPU structure

CPU Timing

The machine cycle consists of a sequence of 6 states, numbered S1 through S6. Each state time lasts for two oscillator periods. Thus a machine cycle takes 12 oscillator periods. Each state is divided into a PHASE 1 half and a PHASE2 half. FIGURE 12 Shows relationships between oscillator, phase, and S1-S6.

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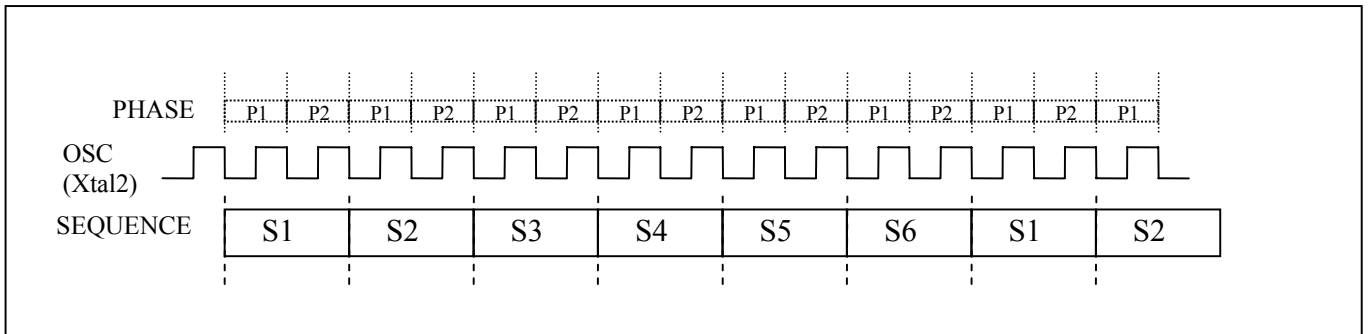


Figure 12 Sequences and Phases

FIGURE 12 shows the fetch / execute sequences in states and phases for various kinds of instructions. Normally the program fetches are generated during each machine cycle, even if the instruction being executed doesn't require it. If the instruction being executed doesn't need more code bytes, the CPU simply ignores the extra fetch, and the PROGRAM COUNTER is incremented accordingly.

Execution of a one-cycle instruction (FIGURE 13A and B) begins during S1 of the machine cycle, when the OPCODE is latched into INSTRUCTION REGISTER. A second fetch occurs during S4 of the same machine cycle. Execution is completed at the end of S6 of this machine cycle.

The MOVX instructions take two machine cycles to execute. No program fetch is generated during the second cycle of a MOVX instruction. This is the only time program fetches are skipped. The fetch/execute sequence for MOVX instructions is shown in FIGURE 13 (D)

The fetch/execute sequences are the same whether the PROGRAM MEMORY is internal or external to the chip. Execution times do not depend on whether the PROGRAM MEMORY is internal or external.

FIGURE 14 shows the signals and timing involved in program fetches when the program memory is external. If PROGRAM MEMORY is external, the PROGRAM MEMORY READ STROBE (/PSEN) is normally activated twice per machine cycle, as shown in FIGURE 14(A).

If an access external DATA MEMORY occurs, as shown in FIGURE 14(B), two (/PSEN) are SKIPPED, because the address and data bus are being used for DATA MEMORY access.

Note that a DATA MEMORY bus cycle takes twice as much time as PROGRAM MEMORY bus cycle. FIGURE 14 shows the relative time of the address begin emitted at PORT0 and PORT2, and of ALE and /PSEN. ALE is used to latch the low address byte from PORT0 into the address latch.

When CPU is executing from internal PROGRAM MEMORY, /PSEN is not activated, and program address is not emitted. However, ALE continues to be activated twice per machine cycle and so is available as clock output signal. Note, however, that ALE is skipped during the execution of the MOVX instruction.

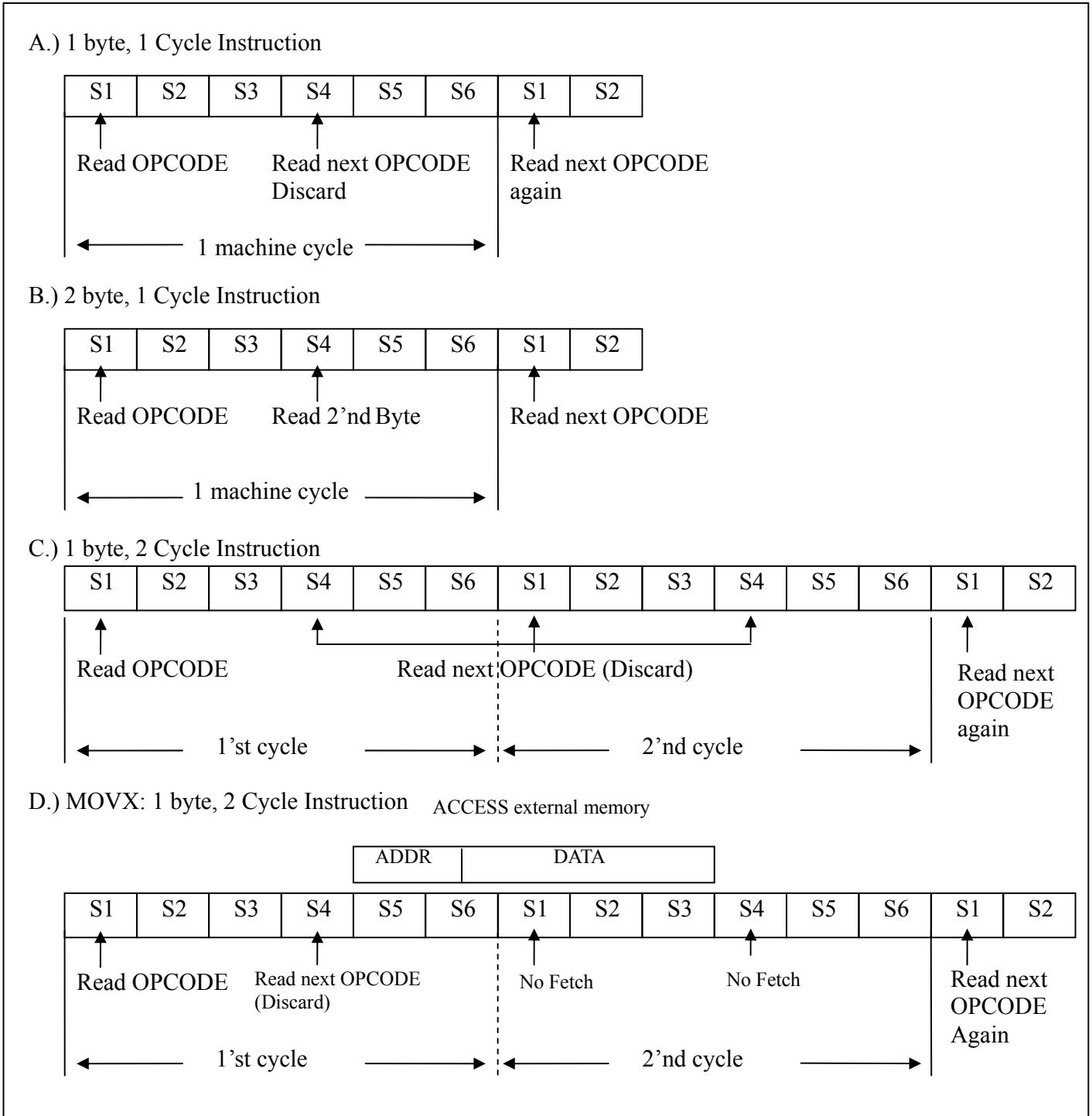


Figure 13 Timing of various instructions

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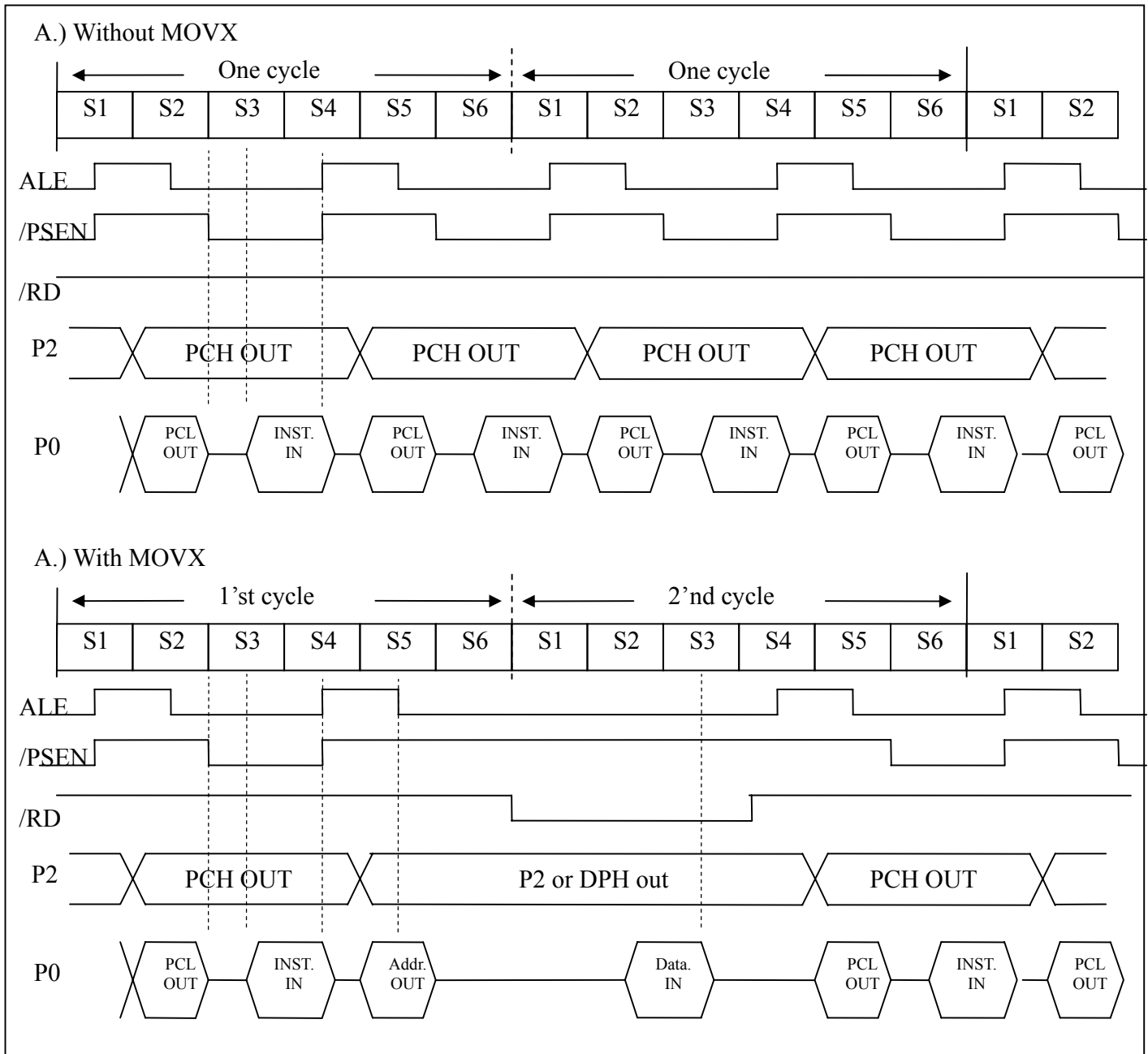


Figure 14: Bus cycle in external program memory mode

Instruction Set

The SM89S16R1 uses the powerful instruction set of 80C51. It consists of 49 single-byte, 42 two-byte, and 15 three-byte instructions. Among them 63 instructions are executed in 1 machine-cycle, 46 instructions in 2 machine-cycles, and the multiply, 2 instructions in 4 machine-cycles.

A summary of the instruction set is given in Table 3.

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Addressing Mode

Notes on instruction set and address modes:

Rn		Register R7-R0 of the currently selected register bank.
direct		8-bits internal data location's address. This could be internal DATA RAM location (0-127) or a SFR [i.e., I/O port, control register, status register, etc. (128-255)]
@Ri		8-bits RAM location addressed indirectly through register R1 or R0 of the actual register bank
#data		8-bits constant included in the instruction
#data16		16-bits constant included in the instruction
addr11		11-bits destination address. Used by ACALL and AJMP. The branch can be anywhere within the same 2 Kbytes page of program memory as the first byte of the following instruction.
rel		Signed (2's complement) 8-bits offset byte. Used by SJMP and all conditional jumps. Range is -128 to +127 bytes relative to first byte of the following instruction.
bit		Direct addressed bit in internal data RAM or SFR

Table 3: A Summary of the instruction set

Mnemonic		OPERATION	BYTE	CYCLE
Arithmetic Instructions				
ADD	A,Rn	$A = A + Rn$	1	1
ADD	A,direct	$A = A + \text{direct}$	2	1
ADD	A,@Ri	$A = A + \langle @Ri \rangle$	1	1
ADD	A,#data	$A = A + \#data$	2	1
ADDC	A,Rn	$A = A + Rn + C$	1	1
ADDC	A,direct	$A = A + \text{direct} + C$	2	1
ADDC	A,@Ri	$A = A + @Ri + C$	1	1
ADDC	A,#data	$A = A + \#data + C$	2	1
SUBB	A,Rn	$A = A - Rn - C$	1	1
SUBB	A,direct	$A = A - \text{direct} - C$	2	1
SUBB	A,@Ri	$A = A - \langle @Ri \rangle - C$	1	1
SUBB	A,#data	$A = A - \#data - C$	2	1
INC	A	$A = A + 1$	1	1
INC	Rn	$Rn = Rn + 1$	1	1
INC	direct	$\text{direct} = \text{direct} + 1$	2	1
INC	@Ri	$\langle @Ri \rangle = \langle @Ri \rangle + 1$	1	1
DEC	A	$A = A - 1$	1	1
DEC	Rn	$Rn = Rn - 1$	1	1
DEC	direct	$\text{direct} = \text{direct} - 1$	2	1
DEC	@Ri	$\langle @Ri \rangle = \langle @Ri \rangle - 1$	1	1
INC	DPTR	$DPTR = DPTR - 1$	1	2
MUL	AB	$B:A = A \times B$	1	4
DIV	AB	$A = \text{INT}(A/B)$ $B = \text{MOD}(A/B)$	1	4
DA	A	Decimal adjust ACC	1	1
Logical Instructions				
ANL	A,Rn	$A \text{ .AND. } Rn$	1	1
ANL	A,direct	$A \text{ .AND. direct}$	2	1
ANL	A,@Ri	$A \text{ .AND. } \langle @Ri \rangle$	1	1
ANL	A,#data	$A \text{ .AND. } \#data$	2	1
ANL	direct,A	$\text{direct} \text{ .AND. } A$	2	1
ANL	direct,#data	$\text{direct} \text{ .AND. } \#data$	3	2
ORL	A,Rn	$A \text{ .OR. } Rn$	1	1
ORL	A,direct	$A \text{ .OR. direct}$	2	1
ORL	A,@Ri	$A \text{ .OR. } \langle @Ri \rangle$	1	1
ORL	A,#data	$A \text{ .OR. } \#data$	2	1
ORL	direct,A	$\text{direct} \text{ .OR. } A$	2	1
ORL	direct,#data	$\text{direct} \text{ .OR. } \#data$	3	2
XRL	A,Rn	$A \text{ .XOR. } Rn$	1	1
XRL	A,direct	$A \text{ .XOR. direct}$	2	1
XRL	A,@Ri	$A \text{ .XOR. } \langle @Ri \rangle$	1	1
XRL	A,#data	$A \text{ .XOR. } \#data$	2	1
XRL	direct,A	$\text{direct} \text{ .XOR. } A$	2	1
XRL	direct,#data	$\text{direct} \text{ .XOR. } \#data$	3	2

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CLR	A	A = 0	1	1
CPL	A	A = /A	1	1
RL	A	Rotate ACC Left 1 bit	1	1
RLC	A	Rotate Left through Carry	1	1
RR	A	Rotate ACC Right 1 bit	1	1
RRC	A	Rotate Right through Carry	1	1
SWAP	A	Swap Nibbles in A	1	1
Data Transfers Instructions				
MOV	A,Rn	A = Rn	1	1
MOV	A,direct	A = direct	2	1
MOV	A,@Ri	A = <@Ri>	1	1
MOV	A,#data	A = #data	2	1
MOV	Rn,A	Rn = A	1	1
MOV	Rn,direct	Rn = direct	2	2
MOV	Rn,#data	Rn = #data	2	1
MOV	direct,A	direct = A	2	1
MOV	direct,Rn	direct = Rn	2	2
MOV	direct,direct	direct = direct	3	2
MOV	direct,@Ri	direct = <@Ri>	2	2
MOV	direct,#data	direct = #data	2	1
MOV	@Ri,A	<@Ri> = A	1	1
MOV	@Ri,direct	<@Ri> = direct	2	2
MOV	@Ri,#data	<@Ri> = #data	2	1
MOV	DPTR,#data16	DPTR = #data16	3	2
MOVC	A,@A+DPTR	A = code memory[A+DPTR]	1	2
MOVC	A,@A+PC	A = code memory[A+PC]	1	2
MOVX	A,@Ri	A = external memory[Ri] (8-bits address)	1	2
MOVX	A,@DPTR	A = external memory[DPTR] (16-bits address)	1	2
MOVX	@Ri,A	external memory[Ri] = A (8-bits address)	1	2
MOVX	@DPTR,A	external memory[DPTR] = A (16-bits address)	1	2
PUSH	direct	INC SP: MOV '@SP', <direct >	2	2
POP	direct	MOV <direct >, '@SP': DEC SP	2	2
XCH	A,Rn	ACC and <Rn > exchange data	1	1
XCH	A,direct	ACC and <direct > exchange data	2	1
XCH	A,@Ri	ACC and <Ri > exchange data	1	1
XCHD	A,@Ri	ACC and @Ri exchange low nibbles	1	1
Boolean Instructions				
CLR	C	C = 0	1	1
CLR	bit	bit = 0	2	1
SETB	C	C = 1	1	1
SETB	bit	bit = 1	2	1
CPL	C	C = /C	1	1
CPL	bit	bit = /bit	2	1
ANL	C,bit	C = C .AND. bit	2	2
ANL	C,/bit	C = C .AND. /bit	2	2
ORL	C,bit	C = C .OR. bit	2	2
ORL	C,/bit	C = C .OR. /bit	2	2
MOV	C,bit	C = bit	2	1
MOV	bit,C	bit = C	2	2
JC	rel	Jump if C = 1	2	2
JNC	rel	Jump if C = 0	2	2
JB	bit,rel	Jump if bit = 1	3	2
JNB	bit,rel	Jump if bit = 0	3	2
JBC	bit,rel	Jump if C = 1	3	2
Jump Instructions				
ACALL	addr11	Call Subroutine only at 2k bytes Address	2	2
LCALL	addr16	Call Subroutine in max 64K bytes Address	3	2
RET		Return from subroutine	1	2
RETI		Return from interrupt	1	2
AJMP	addr11	Jump only at 2k bytes Address	2	2
LJMP	addr16	Jump to max 64K bytes Address	3	2
SJMP	rel	Jump on at 256 bytes	2	2
JMP	@A+DPTR	Jump to A+ DPTR	1	2
JZ	rel	Jump if A = 0	2	2
JNZ	rel	Jump if A ≠ 0	2	2
CJNE	A, direct,rel	Jump if A ≠ <direct >	3	2

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CJNZ	A, #data,rel	Jump if A ≠ < #data >	3	2
CJNZ	Rn, #data,rel	Jump if Rn ≠ < #data >	3	2
CJNZ	@Ri, #data,rel	Jump if @Ri ≠ < #data >	3	2
DJNZ	Rn,rel	Decrement and jump if Rn not zero	2	2
DJNZ	direct,rel	Decrement and jump if direct not zero	3	2
NOP		No Operation	1	1

Memory organization

The central processing unit (CPU) manipulates operands in three memory spaces; there are 1024 bytes internal data memory (consisting of 256 bytes standard RAM and 768 bytes AUX-RAM) and 64K bytes internal/external program memory (see FIGURE 15)

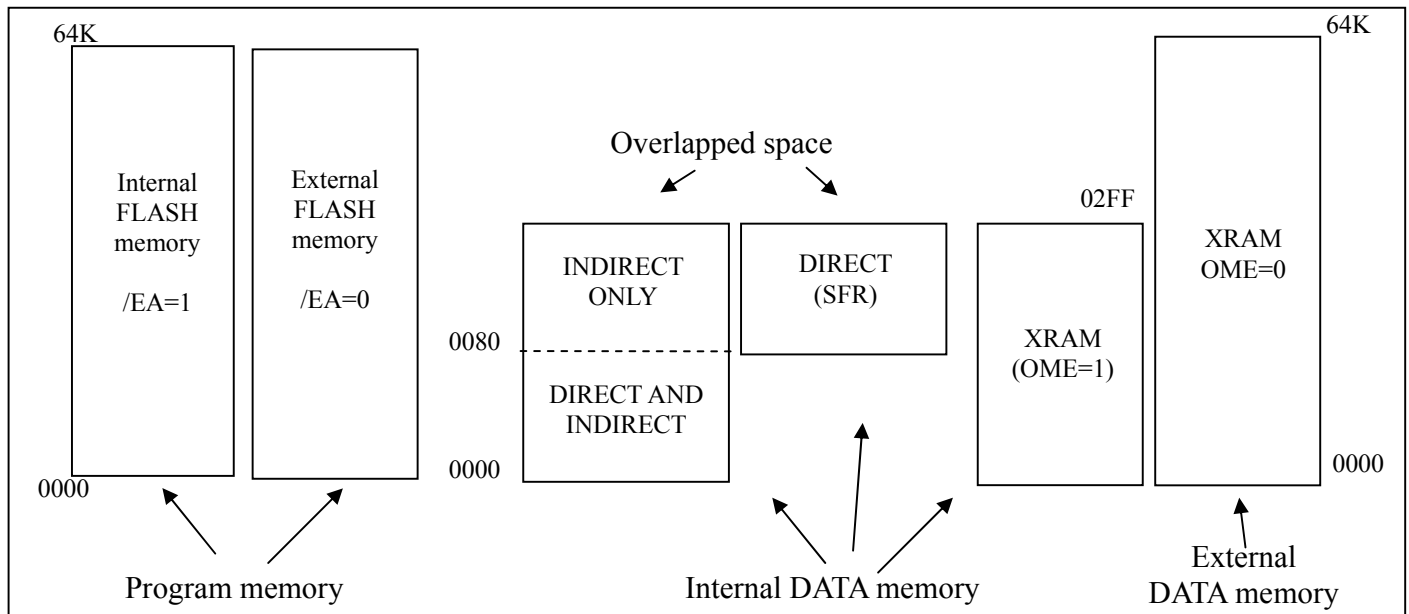


Figure 15 Memory organization of SM89S16R1

Program memory

The program memory of SM89S16R1 consists of 64K bytes FLASH memory on chip. If during RESET, the /EA pin was held high, the SM89S16R1 does not execute out of the internal program memory. If the /EA pin was held low during RESET the SM89S16R1 fetch all instructions from the external program memory.

External writer can program it. The feature of FLASH memory is shown as following :

- **READ:** byte-wise
- **WRITE:** byte-wise within 30us (previously erased by a chip erase).
- **ERASE:**
 - Page Erase (512 bytes) within 10 ms
 - Full Erase (64K bytes) within 2 sec.
 - Erased bytes contain FFH
- **Endurance :** 10K erase and write cycles each byte at TA=25°C
- **Retention :** 10 years

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Internal Data memory

The data memory of SM89S16R1 consists of 1024 bytes internal data memory (256 bytes standard RAM and 768 bytes AUX-RAM). The AUX-RAM is enable by SCONF.1 (\$BF.1), and read/write by MOVX

Analog to Digital Converter (ADC)

The ADC block diagram was shown as below:

Those are only 4 pins mirror to Port 2[7:4] at Vin<3:0>. The digital output DATA [11:4] were put into ADCD (\$8FH). And the ADC interrupt vector is 4BH.

The ADC SFR shown as below:

ADSCR (\$8EH)

Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
Com	Con	ADCSS1	ADCSS0	CH1	CH0		

COM: Read only. When conversion complete, it will be set.

CON: when set, the ADC will conversion continuous, else it will conversion only once.

ADCSS [1:0]: ADC clock select. (ADC_CLK range 500 KHz~2.5 MHz).If over frequency of ADC_CLK, the conversion data may be unstable.

ADCSS1	ADCSS0	ADC_CLK
0	0	FOSC/8
0	1	FOSC/16
1	0	FOSC/32
1	1	FOSC/64

CH [1:0]: ADC channel select.

CH1	CH0	Input select
0	0	CH0
0	1	CH1
1	0	CH2
1	1	CH3

ADCD (\$8FH)

Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
AD.5	AD.4	AD.3	AD.2	AD.1	AD.0		

*Read Only.

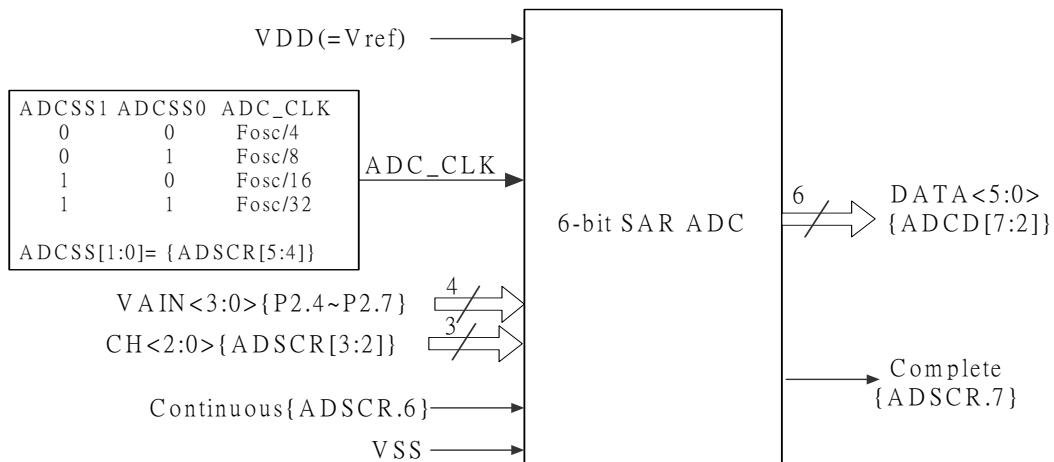


Figure 16 ADC Block Diagram

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Pulse Width Modulation (PWM)

The PWM output pins are P1.4 and P1.5.

The PWM clock is $\{Fosc / (2 \times \text{Divider})\}$, the PWM output frequency is $\{(\text{PWM clock}) / 32\}$ at 5 bits resolution and $\{(\text{PWM clock}) / 256\}$ at 8 bits resolution.

The PWM SFR show as below:

PWMC (\$D3H and \$D4H)

Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
					PBS	PFS1	PFS0

PBS: when set, the PWM is 5 bits resolution.

PFS [1:0]: The PWM clock divider select.

PFS1	PFS0	PWM clock divider select
0	0	2
0	1	4
1	0	8
1	1	16

PWMD (\$B3H and \$B4H)

Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
PWMD.7	PWMD.6	PWMD.5	PWMD.4	PWMD.3	PWMD.2	PWMD.1	PWMD.0

Real Time Clock (RTC)

The on-chip RTC keeps time of second and minute functions. Its time base is a 32.768 KHz crystal between pins X32OUT (alternate function of ALE) and X32IN (alternate function of PSEN). The RTC maintains time to a second.

It also allows a user to read (and write) seconds and minute.

The RTC function used SFR descriptor as below:

RTCS (\$A1H)

Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
RTCCen	Stable	SEC.5	SEC.4	SEC.3	SEC.2	SEC.1	SEC.0

RTCCen: When set to '1', enable the enable RTC function. When this bit set, the ALE and PSEN pins output will disable, and the ALE and PSEN pins will use for RTC function as X32OUT and X32IN.

Stable: Read only. The Stable bit will set to 1 when the RTC module stable. Please wait 2 seconds before used the RTC function.

SEC [5:0]: show the current second counter at RTC function. The range is from 00H to 3BH.

RTCC (\$A2H)

Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
INT_SEL1	INT_SEL0	MIN.5	MIN.4	MIN.3	MIN.2	MIN.1	MIN.0

INT_SEL [1:0]: the interrupt distribution selection bit, the interrupt vector is 43H.

00: the interrupt is set as 0.5 second

01: the interrupt is set as 1 second

10: the interrupt is set as 30 second

11: the interrupt is set as 60 second

MIN [5:0]: show the current minute counter at RTC function. The range is from 00H to 3BH.

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Starting and stopping the RTC:

RTCS (\$A1H)

Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
RTCen	Stable	SEC.5	SEC.4	SEC.3	SEC.2	SEC.1	SEC.0

The RTC Function is enable by set the RTCS.7 (RTCen=1), then the ALE and /PSEN pins will switch to X32OUT and X32IN that for RTC function used, the ALE and PSEN signal output will disable; the crystal frequency is 32.768 KHz. See figure 17.

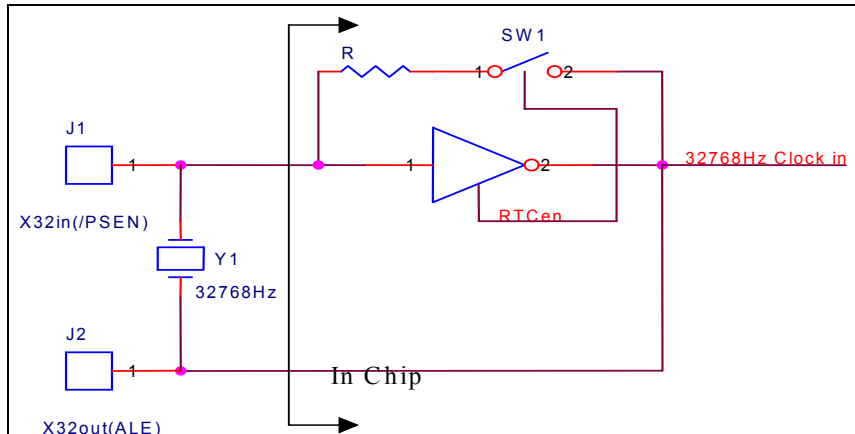


Figure 17 The RTC Crystal connect diagram

The stable bit (RTCS.6) will set to 1 when the RTC module stable. The design is about 31.25 ms; suggest waiting 2 second to use the RTC function. This bit will clear when RTCen bit set again.

The SEC [5:0] will show the second counter (range from 00H to 3BH), and the MIN [5:0] will show the minute counter (range from 00H to 3BH) of RTC function. This two register will clear when RTCen bit set.

Interrupt:

IE1 (\$A9H)

Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
				EADC	ERTC		

ERTC: When set to '1', enable the RTC interrupt. If you want to use the RTC interrupt function, must enable the EA bit in IE.7 and enable the ERTC bit in IE1.2.

EADC: When set to '1', enable the ADC interrupt. If you want to use the ADC interrupt function, must enable the EA bit in IE.7 and enable the EADC bit in IE1.3

RTCC (\$A2H)

Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
INT_SEL1	INT_SEL0	MIN.5	MIN.4	MIN.3	MIN.2	MIN.1	MIN.0

Then select the interrupt distribution in INT_SEL [1:0] in RTCC [7:6].

The RTC can select each of 4 interrupt sources: 0.5 second, 1 second, 0.5 minute, and 1 minute. The interrupt vector is 43H, it can wake-up CPU from POWER-DOWN mode.

IFR (\$AAH)

Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
				ADCIF	RTCIF		

ADCIF: When interrupt occupy the ADC interrupt flag (IFR.3) will set, and the CPU will execute the interrupt subroutine at the interrupt vector 4BH. The ADC Interrupt Flag must clear by software.

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The SM89S16R1 will exit the Power Down mode with a reset or by a RTC (Real Time Clock) interrupt or by an external interrupts pin enabled as level detects.

1. An external reset can be used to exit the Power Down state. The high on RST pin terminates the Power Down mode, and restarts the clock. The program execution will restart from 0000H.
2. An external interrupt pin and RTC interrupt can be used to exit the Power Down state when the external interrupt or RTC interrupt activates and provided the corresponding interrupt is enabled, while the global enable (EA) bit is set and the external input has been set to a level detect mode or RTC interrupt set. If these conditions are met, then the low level on the external pin or RTC interrupt re-starts the oscillator. Then device executes the interrupt service routine for the corresponding external interrupt or RTC interrupt. After the interrupt service routine is completed, the program execution returns to the instruction after the one that put the device into Power Down mode and continues from there.

PCON (\$87H)

Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
SMOD						PD	IDLE

SMOD: This bit set to '1' to make the UART baud-rate double.

PD: When set to '1', the MCU will into Power Down mode

IDLE: When set to '1', the MCU will into IDLE mode

SCONF (\$BFH)

Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
			PDWUE			OME	ALEI

PDWUE: When set to '1', enable the PDWU function.

OME: When set to '1', enable the 768 bytes expanded RAM.

ALEI: When set to '1', it will stop ALE clock output for EMI reduce.

IE (\$A8H)

Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
EA		ET2	ES0	ET1	EX1	ET0	EX0

EA: When set to '1', enable interrupt global.

ET2: When set to '1', enable Timer2 interrupt.

ES0: When set to '1', enable UART interrupt.

ET1: When set to '1', enable Timer1 interrupt.

EX1: When set to '1', enable external interrupt 1.

ET0: When set to '1', enable Timer0 interrupt.

EX0: When set to '1', enable external interrupt 0.

TCON (\$88H)

Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0

TF1: Timer 1 overflow flag.

TR1: Timer 1 run control bit.

TF0: Timer 0 overflow flag.

TR0: Timer 0 run control bit.

IE1: External Interrupt 1 edge flag.

IT1: Interrupt 1 type control bit.

IE0: External Interrupt 0 edge flag.

IT0: Interrupt 0 type control bit.

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IP (\$B8H)

Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
		PT2	PS0	PT1	PX1	PT0	PX0

PT2: Timer2 interrupt priority.
 PS0: UART interrupts priority.
 PT1: Timer1 interrupt priority.
 PX1: external interrupt 1 priority.
 PT0: Timer0 interrupt priority.
 PX0: external interrupt 0 priority.

The Priority structure and vector locations of interrupts:

Source	Flag	Priority level	Vector Address
External interrupt 0	IE0	1(highest)	03H
Timer 0 overflow	TF0	2	0BH
External interrupt 1	IE1	3	13H
Timer 1 overflow	TF1	4	1BH
UART 0 interrupt	RI+TI	5	23H
Timer 2 overflow	TF2+EXF2	6	2BH
RTC interrupt	RTCIF	7	43H
ADC interrupt	ADCIF	8	4BH

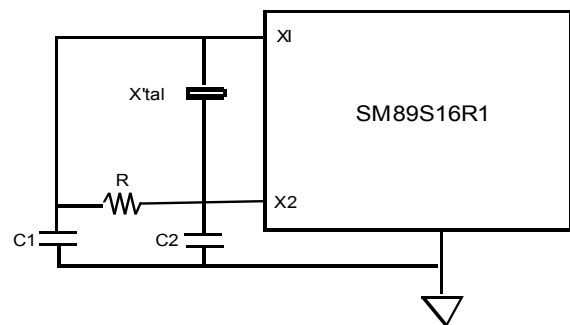
T2MOD (\$C9H)

Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
						T2OE	DCEN

T2CR: Timer 2 Capture Reset. In the Timer2 Capture Mode this bit enables/disables hardware automatically reset Timer2 while the value in TL2 and TH2 have been transferred into the capture register.
 T2OE: Timer2 clock Output Enable bit. If set to 1, the Timer2 clock will output to P1.0.
 DCEN: Down Count Enable. When set this bit then allows Timer2 to be configured as an up/down counter.

Application Reference

Valid for SM89S16R1				
X'tal	3MHz	6MHz	9MHz	12MHz
C1	30 pF	30 pF	30 pF	22 pF
C2	30 pF	30 pF	30 pF	22 pF
R	open	open	open	open
X'tal	16MHz	25MHz	33MHz	40MHz
C1	30 pF	15 pF	5 pF	2 pF
C2	30 pF	15 pF	5 pF	2 pF
R	open	open	6.8K	4.7K



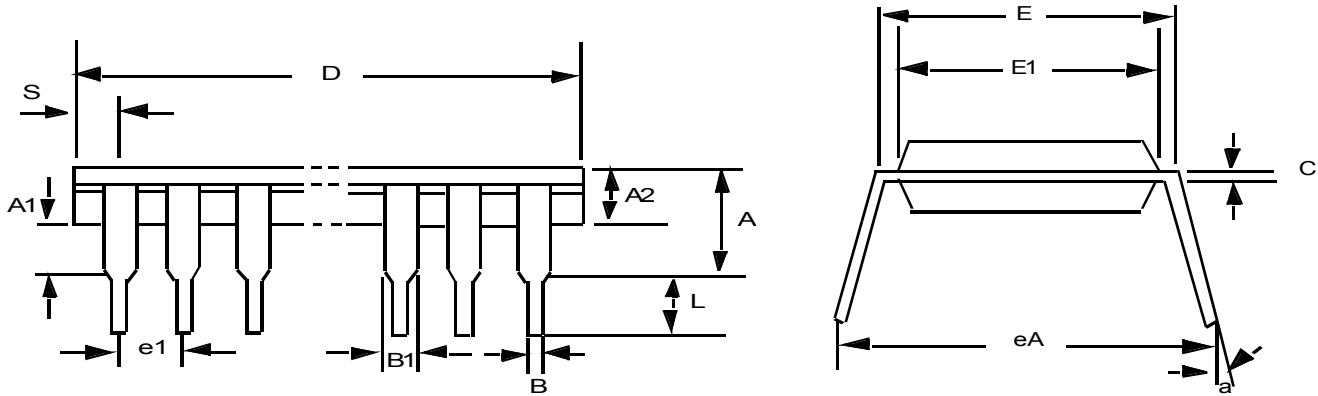
Note:

Oscillation circuit may differs with different crystal or ceramic resonator in higher oscillation frequency which was due to each crystal or ceramic resonator has its own characteristics.
 User should check with the crystal or ceramic resonator manufacturer for appropriate value of external components.

Specifications subject to change without notice contact your sales representatives for the most recent information.



40L 600mil PDIP Information

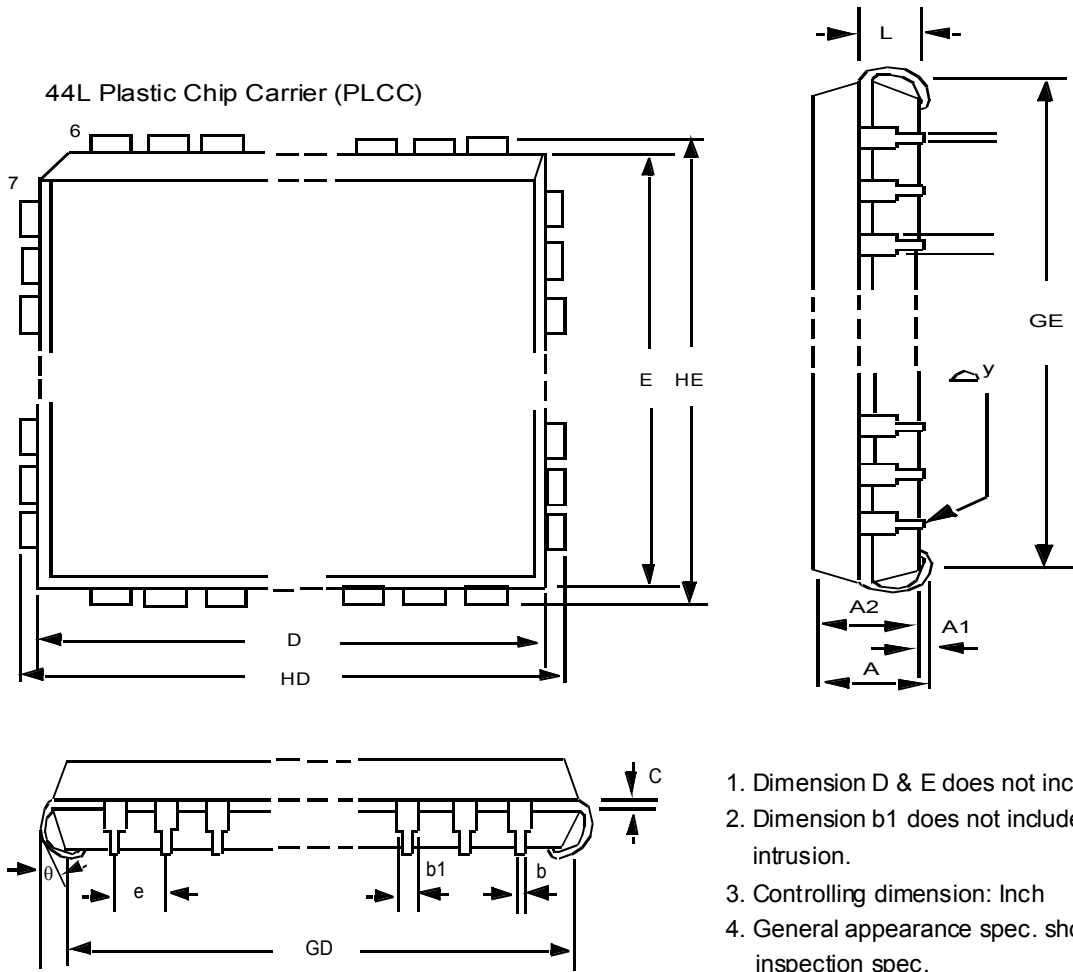


Note:

1. Dimension D Max & include mold flash or tie bar burrs.
2. Dimension E1 does not include inter lead flash.
3. Dimension D & E1 include mold mismatch and are determined at the mold parting line.
4. Dimension B1 does not include dam bar protrusion/infusion.
5. Controlling dimension is inch.
6. General appearance spec. should base on final visual inspection spec.

Symbol	Dimension in inch	
	Minimal / maximal	Minimal / maximal
A	- / 0.210	- / 5.33
A1	0.010 / -	0.25 / -
A2	0.150 / 0.160	3.81 / 4.06
B	0.016 / 0.022	0.41 / 0.56
B1	0.048 / 0.054	1.22 / 1.37
C	0.008 / 0.014	0.20 / 0.36
D	- / 2.070	- / 52.58
E	0.590 / 0.610	14.99 / 15.49
E1	0.540 / 0.552	13.72 / 14.02
e1	0.090 / 0.110	2.29 / 2.79
L	0.120 / 0.140	3.05 / 3.56
a	0 / 15	0 / 15
eA	0.630 / 0.670	16.00 / 17.02
S	- / 0.090	- / 2.29

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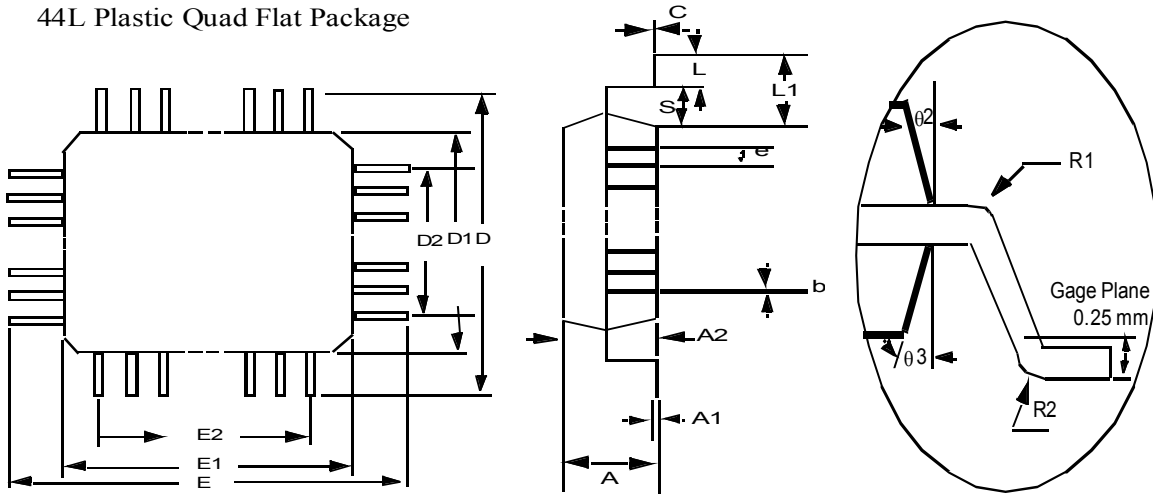
1. Dimension D & E does not include inter lead flash.
2. Dimension b1 does not include dam bar protrusion/ intrusion.
3. Controlling dimension: Inch
4. General appearance spec. should base on final visual inspection spec.

Symbol	Dimension in inch	
	Minimal / maximal	Minimal / maximal
A	- / 0.185	- / 4.70
A1	0.020 / -	0.51 / -
A2	0.145 / 0.155	3.68 / 3.94
b	0.026 / 0.032	0.66 / 0.81
b1	0.016 / 0.022	0.41 / 0.56
C	0.008 / 0.014	0.20 / 0.36
D	0.648 / 0.658	16.46 / 16.71
E	0.648 / 0.658	16.46 / 16.71
e	0.050 BSC	1.27 BSC
GD	0.590 / 0.630	14.99 / 16.00
GE	0.590 / 0.630	14.99 / 16.00
HD	0.680 / 0.700	17.27 / 17.78
HE	0.680 / 0.700	17.27 / 17.78
L	0.090 / 0.110	2.29 / 2.79
θ	- / 0.004	- / 0.10
y	/	/

Specifications subject to change without notice contact your sales representatives for the most recent information.



44L Plastic Quad Flat Package

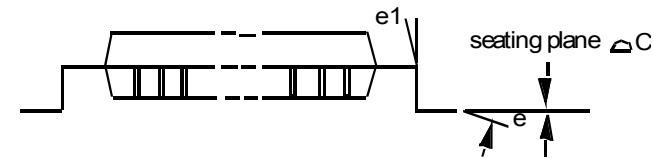


Note:

Dimension D1 and E1 do not include mold protrusion. Allowance protrusion is 0.25mm per side.

Dimension D1 and E1 do include mold mismatch and are determined datum plane.

Dimension b does not include dam bar protrusion. Allowance dam bar protrusion shall be 0.08 mm total in excess of the b dimension at maximum material condition. Dam bar cannot be located on the lower radius or the lead foot.



Symbol	Dimension in inch	
	Minimal / maximal	Minimal / maximal
A	- / 0.100	- / 2.55
A1	0.006 / 0.014	0.15 / 0.35
A2	0.071 / 0.087	1.80 / 2.20
b	0.012 / 0.018	0.30 / 0.45
c	0.004 / 0.009	0.09 / 0.20
D	0.520 BSC	13.20 BSC
D1	0.394 BSC	10.00 BSC
D2	0.315	8.00
E	0.520 BSC	13.20 BSC
E1	0.394 BSC	10.00 BSC
E2	0.315	8.00
e	0.031 BSC	0.80 BSC
L	0.029 / 0.041	0.73 / 1.03
L1	0.063	1.60
R1	0.005 / -	0.13 / -
R2	0.005 / 0.012°C	0.13 / 0.30
S	0.008 / -	0.20 / -
θ	0°C / 7°C	as left
θ1	0°C / -	as left
θ2	10°C REF	as left
θ3	7°C REF	as left
△C	0.004	0.10

Specifications subject to change without notice contact your sales representatives for the most recent information.